

Amendments to the Specification:

Please replace the text at p. 150, line 1-p. 151, line 6 with the following rewritten text:

ABSTRACT

~~The present invention relates to thermosetting~~ Thermosetting resin compositions ~~which are suitably used for manufacturing circuit boards, such as flexible printed circuit boards (FPCs) and build-up circuit boards, and to multilayer bodies and circuit boards manufactured using such thermosetting resin~~ these compositions are provided. A ~~thermosetting resin~~ composition contains a polyimide resin component (A), a phenol resin component (B), and an epoxy resin component (C) components. The mixing ratio by weight (A)/[(B)+(C)] is ~~in a range of~~ 0.4 to 2.0, the ~~mixing ratio by weight~~ being the ratio of the weight of the component (A) to the total weight of the component (B) and the component (C). By using such a ~~thermosetting resin~~ composition, it is ~~possible to manufacture~~ multilayer bodies and circuit boards, ~~which are~~ excellent in dielectric characteristics, adhesiveness, processability, heat resistance, flowability, etc. can be manufactured. A ~~thermosetting resin~~ composition contains a polyimide resin (A), a phosphazene compound (D), and a cyanate ester compound (E). ~~The phosphazene compound (D)~~ D includes a phenolic hydroxyl group-containing phenoxyphosphazene compound (D-1) and/or a crosslinked phenoxyphosphazene compound (D-2) prepared by crosslinking ~~the phenoxyphosphazene compound (D-1), the crosslinked phenoxyphosphazene compound (D-2)~~ having at least one phenolic hydroxyl group. By using such a ~~thermosetting resin~~ composition, it is ~~possible to manufacture~~ multilayer bodies and circuit boards ~~which are~~ with excellent properties can be

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manufactured in dielectric characteristics, processability, heat resistance, and flame retardance.